

## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

<b>Title of Invention</b>	NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE AND INTERFACE ROUGHNESS OF ELECTRICALLY CONDUCTING LINES IN SEMICONDUCTOR INTEGRATED CIRCUITS IN DEEP SUB-MICRON REGIME	
Application Number :		
Date :		
First Named Applicant:	Fen Chen	
Confirmation Number:		
Attorney Docket Number:	BUR920040182US1	
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Documents being submitted:	Files
us-fee-sheet	BUR920040182US1-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	BUR920040182US1-usidst.xml us-ids.dtd us-ids.xsl
us-assignment	BUR920040182US1-usassn.xml us-assignment.xsl us-assignment.dtd BUR920040182Assign1.tif BUR920040182Assign2.tif
us-request	BUR920040182US1-usreq.xml us-request.dtd us-request.xsl
application-body	BUR920040182ABX.xml application-body.dtd Image1.tif Image2.tif Image3.tif Image4.tif isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isogrk1.ent isogrk2.ent isogrk3.ent isogrk4.ent isolat1.ent isolat2.ent isomfrk.ent isomopf.ent isomscr.ent isonum.ent isopub.ent isotech.ent mathml2.dtd mathml2-qname-1.mod mmlalias.ent mmlextra.ent soextblk.dtd us-application-body.xsl wipo.ent

application-body-pdf-wrap	BUR920040182ABX-pdf-wrap.xml
abstract-pdf	BUR920040182ABX-abst.pdf
claims-pdf	BUR920040182ABX-clms.pdf
description-pdf	BUR920040182ABX-desc.pdf
drawings-pdf	BUR920040182ABX-draw.pdf
us-declaration	BUR920040182dec1.tif
us-declaration	BUR920040182dec2.tif

**Comments**

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